Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	17-10-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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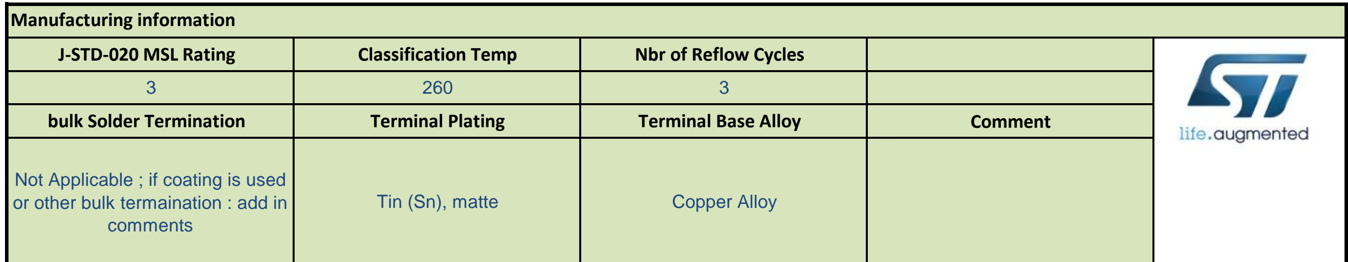
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32H7R3V8T6	E01L*485XXXY	A	9991	17-10-2023
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	681.44	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	**Size**	**Nbr of instances**	**Shape**	
QFP	14x14	100	L bend	
Comment	Package : 1L LQFP 100 14x14x1.4 1 0086901			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-14th June 2023				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**TRUE**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E01L*485XXXY				6000000.0	1000001.0
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	13.101	mg	supplier	die	Silicon (Si)	7440-21-3		12.629	mg	963972	18533
				supplier	metallization	Aluminium (Al)	7429-90-5		0.056	mg	4274	82
				supplier	metallization	Copper (Cu)	7440-50-8		0.175	mg	13358	257
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	76	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	2214	43
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	382	7
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	76	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.205	mg	15648	301
Leadframe (C7025 + Ag)	Copper & its alloys	190.000	mg	Supplier	Leadframe	Copper (Cu)	7440 – 50 - 8		179.360	mg	944000	263207
				Supplier	Leadframe	Silver (Ag)	7440 – 22 – 4		2.850	mg	15000	4182
				Supplier	Leadframe	Magnesium (Mg)	7439 – 95 – 4		0.333	mg	1750	488
				Supplier	Leadframe	Silicon (Si)	7440 – 21 – 3		1.378	mg	7250	2021
				Supplier	Leadframe	Nickel (Ni)	7440 - 02 – 0		6.080	mg	32000	8922
Glue epoxy (CRM 1076WA)	Precious metals	2.600	mg	Supplier	Glue or tape	Silver Powder	7440-22-4		1.986	mg	764000	2915
				Supplier	Glue or tape	Bisphenol F Type Epoxy Resin	9003-36-5		0.078	mg	30000	114
				Supplier	Glue or tape	Epoxy resin	Proprietary		0.156	mg	60000	229
				Supplier	Glue or tape	Hardener	Proprietary		0.078	mg	30000	114
				Supplier	Glue or tape	Ethylene dimethacrylate	97-90-5		0.195	mg	75000	286
				Supplier	Glue or tape	1,4-Cyclohexanedimethanol diglycidyl ether	14228-73-0		0.078	mg	30000	114
				Supplier	Glue or tape	Dicyandiamide	461-58-5		0.014	mg	5500	21
				Supplier	Glue or tape	1,1-Di(t-butylperoxy)cyclohexane	3006-86-8		0.014	mg	5500	21
Bonding wire (Au)	Precious metals	2.800	mg	Supplier	Bonding wire	Gold (Au)	7440-57-5		2.768	mg	988500	4062
				Supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.032		11500	47
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	452.040	mg	Supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4	85954-11-6		18.082	mg	40000	26534
				Supplier	Molding Compound	Epoxy resin	Proprietary		9.041	mg	20000	13267
				Supplier	Molding Compound	Phenol Resin	Proprietary		33.903	mg	75000	49752
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		320.722	mg	709500	470654
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		67.806	mg	150000	99504
				Supplier	Molding Compound	Carbon black	1333-86-4		2.486	mg	5500	3648
External Plating (Sn)	M-011 Other inorganic materials	20.900	mg	Supplier	Matte Sn	Tin (Sn)	7440-31-5		20.898	mg	999900	30667
				Supplier	Matte Sn	Impurities	-		0.002	mg	100	3